

Amendments to the Claims:

This listing of claims will replace all prior versions, and listings, of claims in the application:

Listing of Claims:

1. (currently amended) A non-sensitizing epoxy composition comprising:
an uncured epoxy resin composition including a liquid epoxy resin and a non-sensitizing mercaptan composition capable of curing said epoxy resin when combined with said mercaptan composition to form a substantially uniform mixture, wherein said epoxy resin has a molecular weight greater than of about 700 800-1000, said epoxy resin being admixed with fillers and colorants selected from the group consisting of talc, titanium dioxide, carbon black and mixtures thereof.
2. (original) The composition as recited in claim 1, wherein said epoxy resin is about 20-30% by weight of said uncured epoxy resin composition.
3. (canceled)
4. (canceled)
5. (currently amended) The composition as recited in claim 3 1, wherein said epoxy resin has a molecular weight of from about 900-950.
6. (original) The composition as recited in claim 1, wherein said liquid epoxy resin is a sorbitol glycidyl ether-aliphatic polyfunctional epoxy resin.
7. (original) The composition as recited in claim 1, wherein said epoxy resin has the consistency of a stiff epoxy putty.
8. (original) The composition as recited in claim 1, wherein said epoxy putty composition has the consistency of a liquid or paste.
9. (withdrawn) A non-sensitizing epoxy composition comprising:
a first band of an uncured epoxy resin composition including a liquid epoxy resin and a second band, said bands being joined in close side-by-side relation throughout their entire length, said second band comprising a non-sensitizing mercaptan composition

capable of curing said epoxy resin when said first and second bands are combined to form a substantially uniform mixture, wherein said epoxy resin has a molecular weight greater than about 700.

10. (currently amended) A method of forming a non-sensitizing epoxy putty composition, comprising:

combining an uncured epoxy resin composition including a liquid epoxy resin and a non-sensitizing mercaptan composition capable of curing said epoxy resin when combined with said mercaptan composition to form a substantially uniform mixture, wherein said epoxy resin has a molecular weight greater than of about 700 800-1000, said epoxy resin being admixed with fillers and colorants selected from the group consisting of talc, titanium dioxide, carbon black and mixtures thereof.

11. (original) The method as recited in claim 10, wherein said epoxy resin is about 20-30% by weight of said uncured epoxy resin composition.

12. (canceled)

13. (canceled)

14. (original) The method as recited in claim 10, wherein said epoxy resin has a molecular weight of from about 900-950.

15. (original) The method as recited in claim 10, wherein said liquid epoxy resin is a sorbitol glycidyl ether-aliphatic polyfunctional epoxy resin.

16. (original) The composition as recited in claim 10, wherein said epoxy resin has the consistency of a stiff epoxy putty.

17. (original) The method as recited in claim 10, wherein said epoxy putty composition has the consistency of a liquid or paste.